



Institut luxembourgeois de la normalisation  
de l'accréditation, de la sécurité et qualité  
des produits et services

## ILNAS-EN IEC 62025-2:2019

### **High frequency inductive components - Non-electrical characteristics and measuring methods - Part 2: Test methods for non-electrical**

Composants inductifs à haute fréquence  
- Caractéristiques non électriques et  
méthodes de mesure - Partie 2: Méthodes  
d'essai pour caractéristiques non

Induktive Hochfrequenzbauelemente -  
Nichtelektrische Eigenschaften und  
Messmethoden - Teil 2: Messverfahren für  
nichtelektrische Eigenschaften

11/2019



## National Foreword

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ILNAS-EN IEC 62025-2:2019

EUROPEAN STANDARD **EN IEC 62025-2**  
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Supersedes EN 62025-2:2005 and all of its amendments  
and corrigenda (if any)

English Version

High frequency inductive components - Non-electrical  
characteristics and measuring methods - Part 2: Test methods  
for non-electrical characteristics  
(IEC 62025-2:2019)

Composants inductifs à haute fréquence - Caractéristiques  
non électriques et méthodes de mesure - Partie 2:  
Méthodes d'essai pour caractéristiques non électriques  
(IEC 62025-2:2019)

Induktive Hochfrequenzbauelemente - Nichtelektrische  
Eigenschaften und Messmethoden - Teil 2: Messverfahren  
für nichtelektrische Eigenschaften  
(IEC 62025-2:2019)

This European Standard was approved by CENELEC on 2019-10-25. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels**

## European foreword

The text of document 51/1273/CDV, future edition 2 of IEC 62025-2, prepared by IEC/TC 51 "Magnetic components, ferrite and magnetic powder materials" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62025-2:2019.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2020-07-25
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2022-10-25

This document supersedes EN 62025-2:2005 and all of its amendments and corrigenda (if any).

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## Endorsement notice

The text of the International Standard IEC 62025-2:2019 was approved by CENELEC as a European Standard without any modification.

## Annex ZA

(normative)

### Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

| <u>Publication</u> | <u>Year</u> | <u>Title</u>                                                                                                                                                                           | <u>EN/HD</u>  | <u>Year</u> |
|--------------------|-------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------|-------------|
| IEC 60068-1        | -           | Environmental testing - Part 1: General and guidance                                                                                                                                   | EN 60068-1    | -           |
| IEC 60068-2-6      | 2007        | Environmental testing - Part 2-6: Tests - Test Fc: Vibration (sinusoidal)                                                                                                              | EN 60068-2-6  | 2008        |
| IEC 60068-2-20     | -           | Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads                                               | EN 60068-2-20 | -           |
| IEC 60068-2-21     | 2006        | Environmental testing - Part 2-21: Tests - Test U: Robustness of terminations and integral mounting devices                                                                            | EN 60068-2-21 | 2006        |
| IEC 60068-2-27     | -           | Environmental testing - Part 2-27: Tests - Test Ea and guidance: Shock                                                                                                                 | EN 60068-2-27 | -           |
| IEC 60068-2-45     | 1980        | Basic environmental testing procedures - Part 2-45: Tests - Test XA and guidance: Immersion in cleaning solvents                                                                       | EN 60068-2-45 | 1992        |
| + A1               | 1993        |                                                                                                                                                                                        | + A1          | 1993        |
| IEC 60068-2-58     | 2015        | Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD) | EN 60068-2-58 | 2015        |
| + A1               | 2017        |                                                                                                                                                                                        | + A1          | 2018        |
| IEC 60068-2-69     | -           | Environmental testing - Part 2-69: Tests - Test Te/Tc: Solderability testing of electronic components and printed boards by the wetting balance (force measurement) method             | EN 60068-2-69 | -           |
| IEC 60068-2-77     | -           | Environmental testing - Part 2-77: Tests - Test 77: Body strength and impact shock                                                                                                     | EN 60068-2-77 | -           |

| <u>Publication</u> | <u>Year</u> | <u>Title</u>                                                                                                                                                                          | <u>EN/HD</u>       | <u>Year</u> |
|--------------------|-------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------|-------------|
| IEC 61188-5-2      | -           | Printed boards and printed board assemblies - Design and use - Part 5-2: Attachment (land/joint) considerations - Discrete components                                                 | EN 61188-5-2       | -           |
| IEC 61190-1-2      | 2014        | Attachment materials for electronic assembly - Part 1-2: Requirements for soldering pastes for high-quality interconnects in electronics assembly                                     | EN 61190-1-2       | 2014        |
| IEC 61190-1-3      | -           | Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications | EN IEC 61190-1-3 - |             |
| IEC 62211          | 2017        | Inductive components – Reliability management                                                                                                                                         | EN 62211           | 2017        |



# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

**High frequency inductive components – Non-electrical characteristics and measuring methods –**

**Part 2: Test methods for non-electrical characteristics**

**Composants inductifs à haute fréquence – Caractéristiques non électriques et méthodes de mesure –**

**Partie 2: Méthodes d'essai pour caractéristiques non électriques**

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